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(12) **United States Design Patent**
Imamura et al.

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(54) **SEMICONDUCTOR DEVICE**
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(**) Term: **15 Years**

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(52) **U.S. Cl.**
USPC **D13/182**

(58) **Field of Classification Search**
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D13/199
CPC .. H05K 1/18; H05K 7/00; H05K 7/20; H02M
7/00; H01L 25/07; H01L 25/16; H01L
25/18; H01L 23/00; H01L 23/31
See application file for complete search history.

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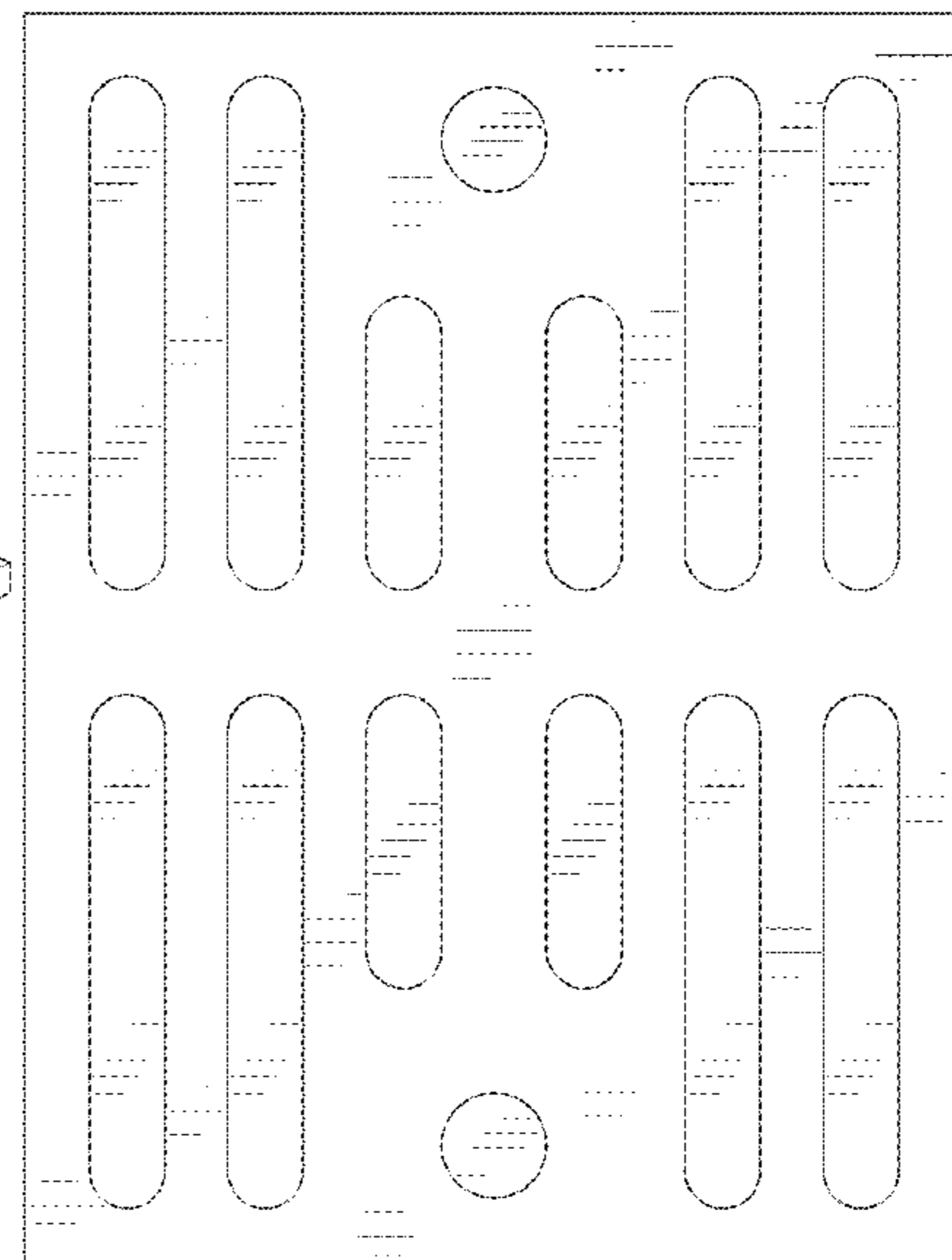
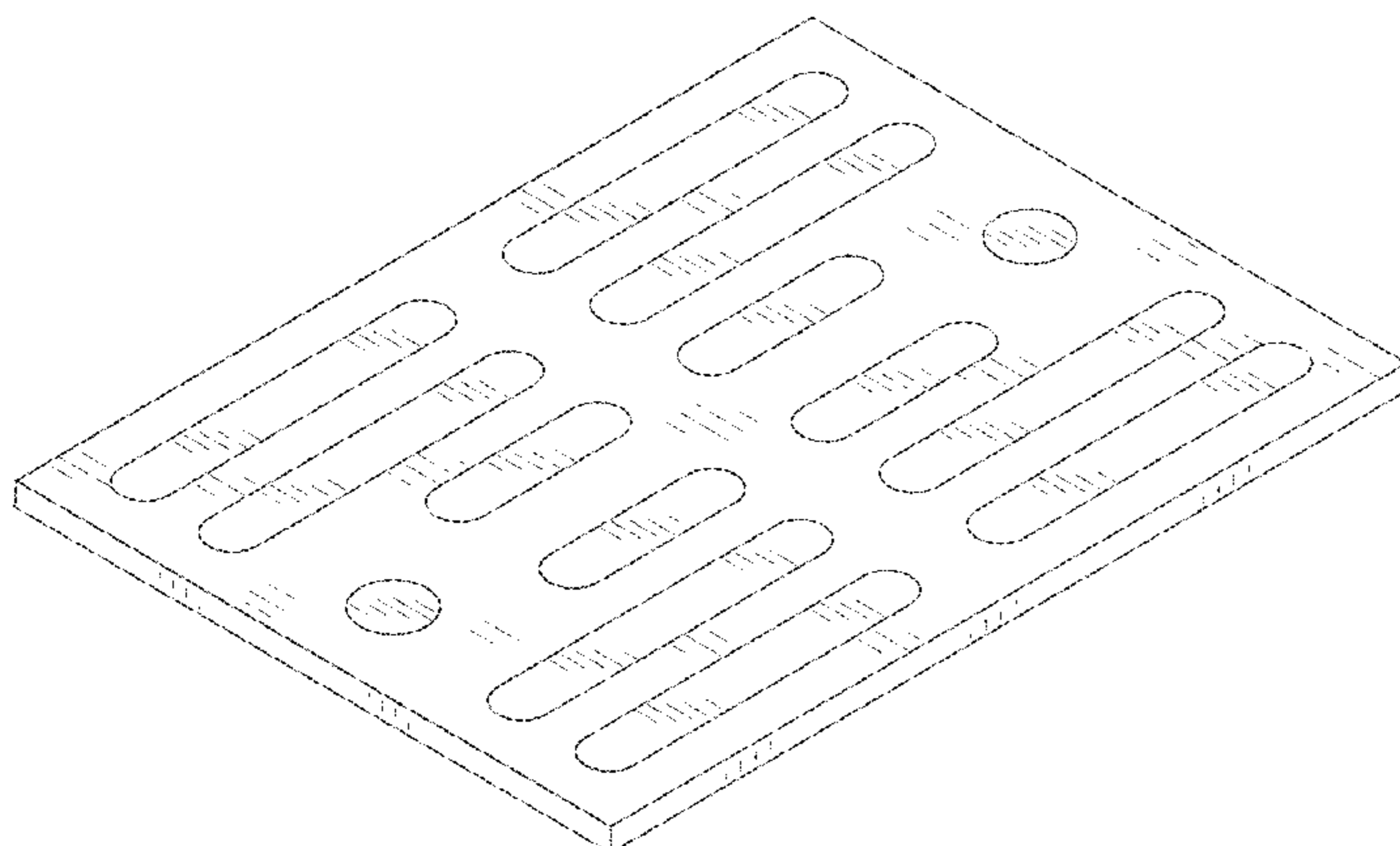
(57) **CLAIM**

We claim the ornamental design for a semiconductor device, as shown and described.

DESCRIPTION

FIG. 1 is a front perspective view of a semiconductor device showing our new design;
FIG. 2 is a front view thereof;
FIG. 3 is a rear view thereof;
FIG. 4 is a left side view thereof;
FIG. 5 is a right side view thereof;
FIG. 6 is a top plan view thereof; and,
FIG. 7 is a bottom view thereof.

1 Claim, 7 Drawing Sheets



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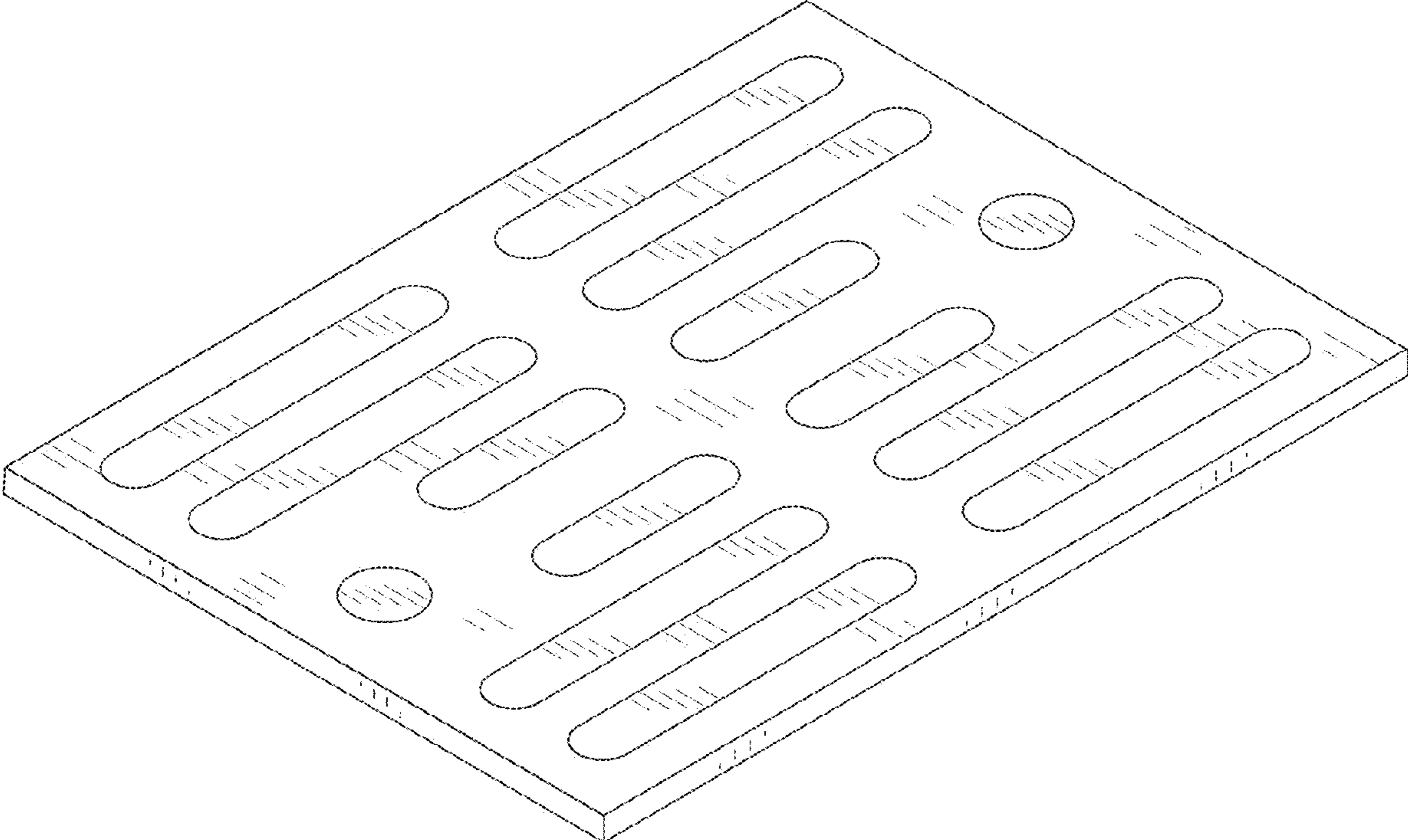


FIG. 1

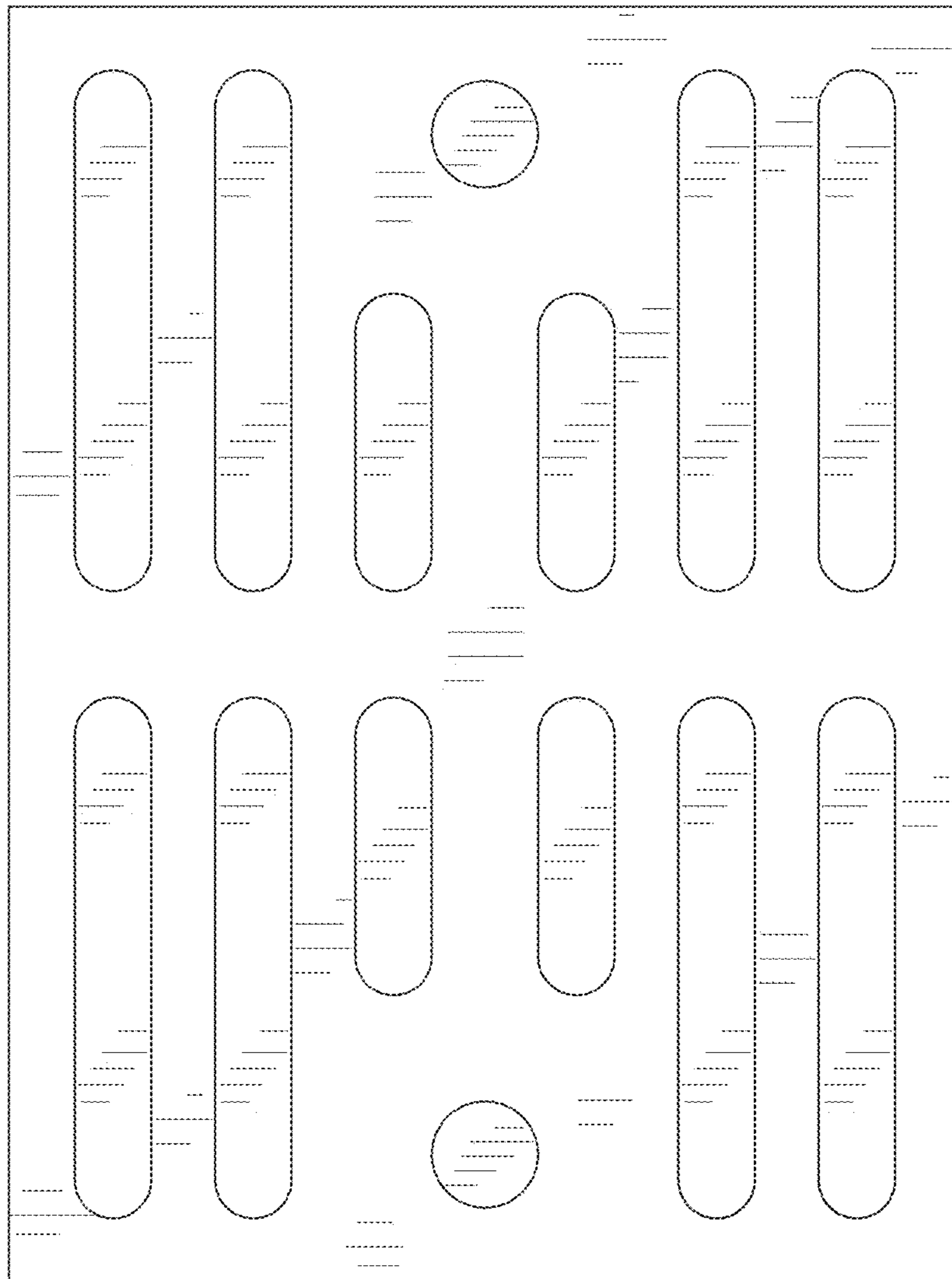


FIG. 2

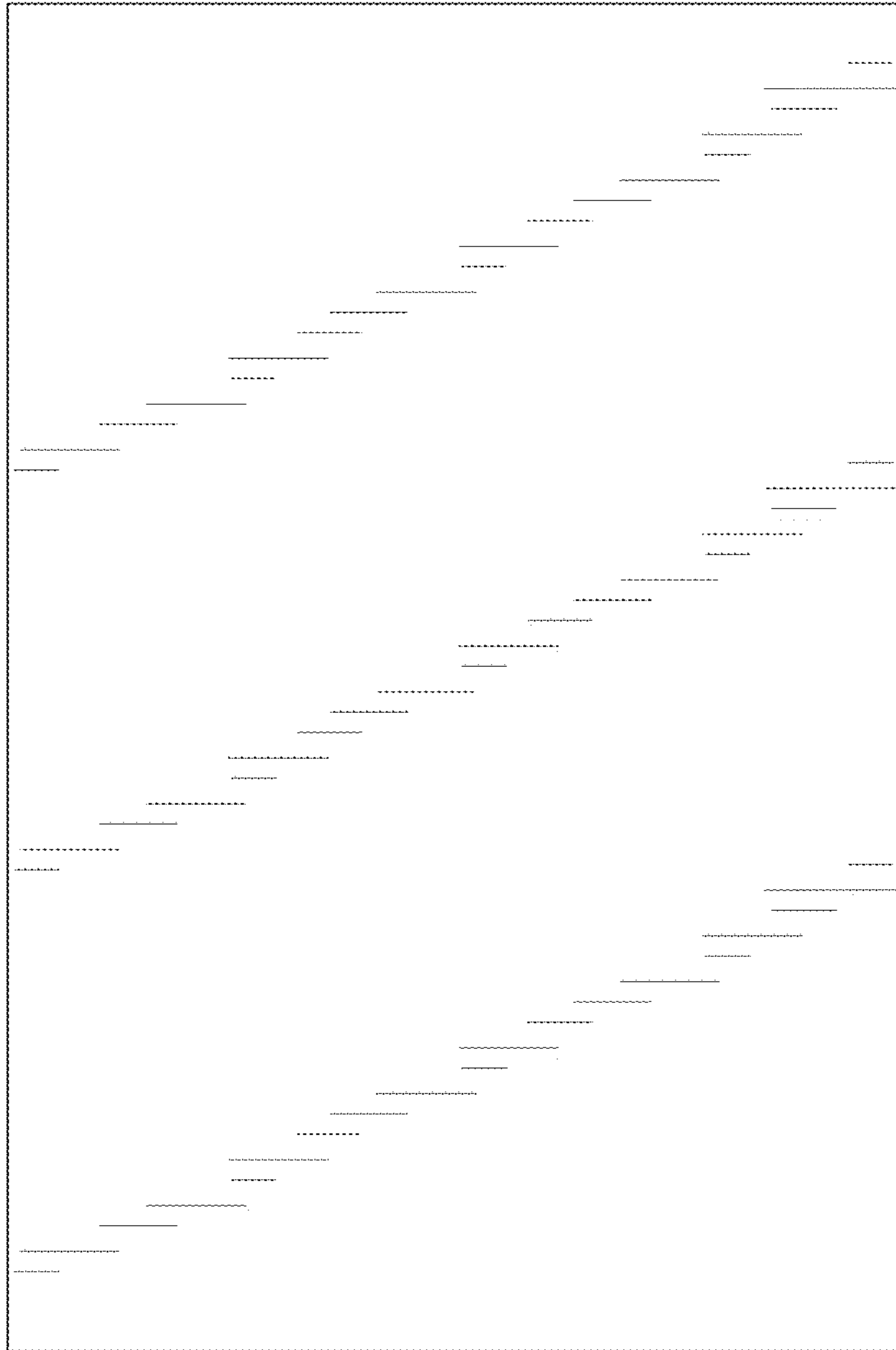


FIG. 3



FIG.4



FIG. 5



FIG.6



FIG.7